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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Obsolete
Core Processor	Z8
Core Size	8-Bit
Speed	10MHz
Connectivity	-
Peripherals	PWM, WDT
Number of I/O	13
Program Memory Size	1KB (1K x 8)
Program Memory Type	OTP
EEPROM Size	-
RAM Size	64 x 8
Voltage - Supply (Vcc/Vdd)	4.5V ~ 5.5V
Data Converters	-
Oscillator Type	Internal
Operating Temperature	-40°C ~ 105°C (TA)
Mounting Type	Through Hole
Package / Case	18-DIP (0.300", 7.62mm)
Supplier Device Package	-
Purchase URL	https://www.e-xfl.com/product-detail/zilog/z8e00110pec

GENERAL DESCRIPTION (Continued)

ing real-time tasks such as counting/timing and I/O data communications.

Note: All signals with an overline, " ", are active Low. For example, B/W (WORD is active Low, only); B/W (BYTE is active Low, only).

Power connections follow conventional descriptions below:

Connection	Circuit	Device
Power	V_{CC}	V_{DD}
Ground	GND	V_{SS}

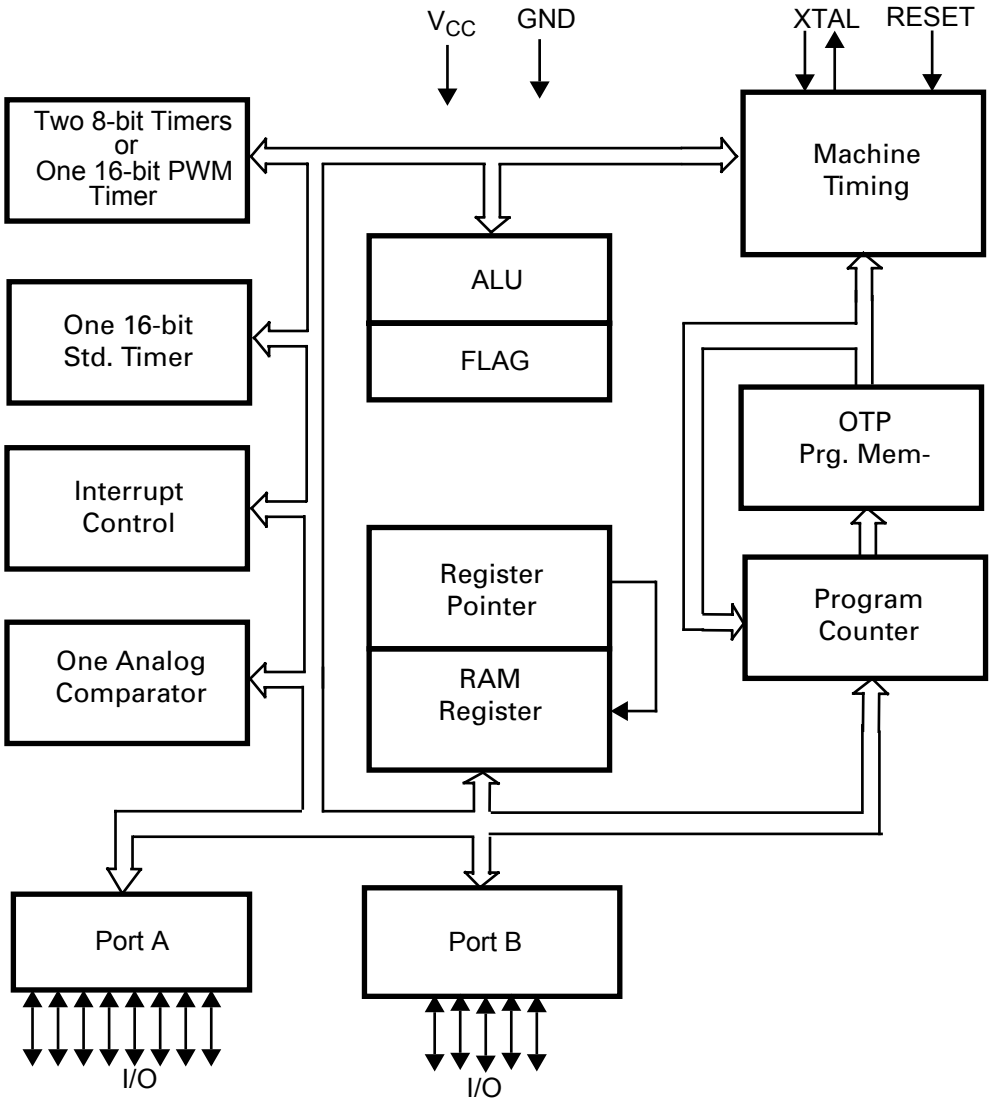


Figure 1. Functional Block Diagram

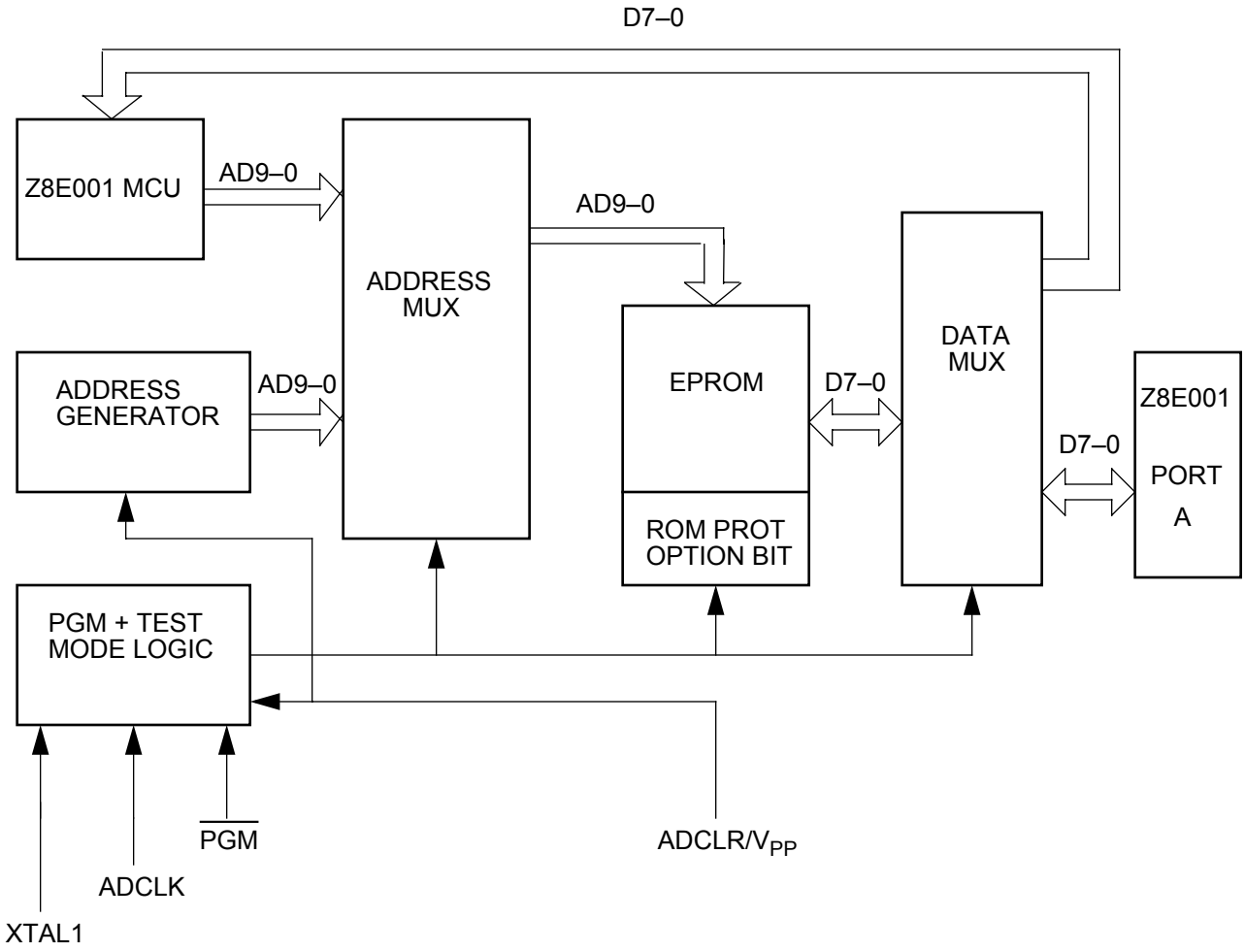


Figure 2. EPROM Programming Mode Block Diagram

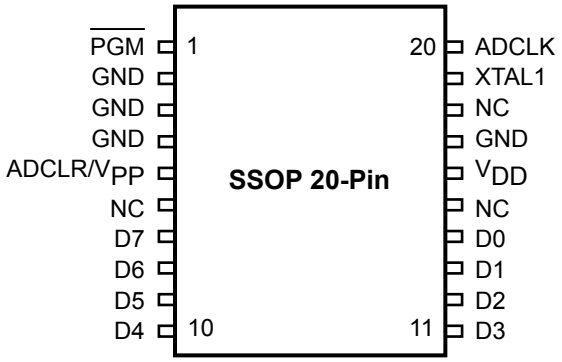


Figure 6. 20-Pin SSOP Pin Identification/EPROM Programming Mode

EPROM Programming Mode

Pin #	Symbol	Function	Direction
1	$\overline{PGM}$	Prog Mode	Input
2–4	GND	Ground	
5	ADCLR/V_{PP}	Clear Clk./Prog Volt.	Input
6	NC	No Connection	
7–10	D7–D4	Data 7,6,5,4	Input/Output
11–14	D3–D0	Data 3,2,1,0	Input/Output
15	NC	No Connection	
16	V_{DD}	Power Supply	
17	GND	Ground	
18	NC	No Connection	
19	XTAL1	1MHz Clock	Input
20	ADCLK	Address Clock	Input

ABSOLUTE MAXIMUM RATINGS

Parameter	Min	Max	Units	Note
Ambient Temperature under Bias	–40	+105	C	
Storage Temperature	–65	+150	C	
Voltage on any Pin with Respect to V_{SS}	–0.6	+7	V	1
Voltage on V_{DD} Pin with Respect to V_{SS}	–0.3	+7	V	
Voltage on $\overline{\text{RESET}}$ Pin with Respect to V_{SS}	–0.6	V_{DD}+1	V	2
Total Power Dissipation		880	mW	
Maximum Allowable Current out of V_{SS}		80	mA	
Maximum Allowable Current into V_{DD}		80	mA	
Maximum Allowable Current into an Input Pin	–600	+600	mA	3
Maximum Allowable Current into an Open-Drain Pin	–600	+600	mA	4
Maximum Allowable Output Current Sunk by Any I/O Pin		25	mA	
Maximum Allowable Output Current Sourced by Any I/O Pin		25	mA	
Maximum Allowable Output Current Sunk by Port A		40	mA	
Maximum Allowable Output Current Sourced by Port A		40	mA	
Maximum Allowable Output Current Sunk by Port B		40	mA	
Maximum Allowable Output Current Sourced by Port B		40	mA	

Notes:
1. Applies to all pins except the $\overline{\text{RESET}}$ pin and where otherwise noted.
2. There is no input protection diode from pin to V_{DD}.
3. Excludes XTAL pins.
4. Device pin is not at an output Low state.

Stresses greater than those listed under Absolute Maximum Ratings can cause permanent damage to the device. This rating is a stress rating only. Functional operation of the device at any condition above those indicated in the operational sections of these specifications is not implied. Exposure to absolute maximum rating conditions for an extended period can affect device reliability. Total power dissipation should not exceed 880 mW for the package. Power dissipation is calculated as follows:

$$\text{Total Power Dissipation} = V_{DD} \times [I_{DD} - (\text{sum of } I_{OH})] + \text{sum of } [(V_{DD} - V_{OH}) \times I_{OH}] + \text{sum of } (V_{0L} \times I_{0L})$$

STANDARD TEST CONDITIONS

The characteristics listed below apply for standard test conditions as noted. All voltages are referenced to Ground. Positive current flows into the referenced pin (Figure 7).

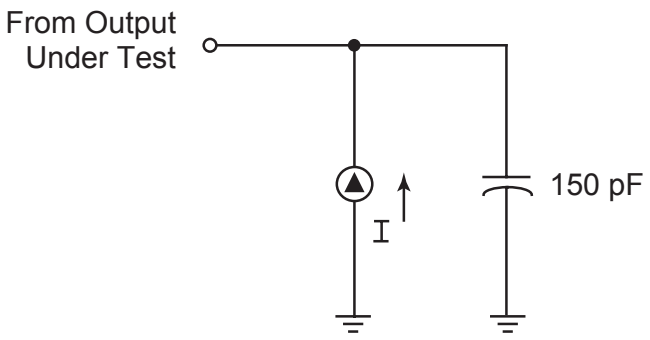


Figure 7. Test Load Diagram

CAPACITANCE

T_A = 25°C, V_{CC} = GND = 0V, f = 1.0 MHz, unmeasured pins returned to GND.

Parameter	Min	Max
Input capacitance	0	12 pF
Output capacitance	0	12 pF
I/O capacitance	0	12 pF

DC ELECTRICAL CHARACTERISTICS

Table 1. DC Electrical Characteristics

			pF T_A = 0°C to +70°C Standard Temperatures					
Sym	**Parameter**	**V_{CC}[1]**	**Min**	**Max**	**Typical[2] @ 25°C**	**Units**	**Conditions**	**Notes**
V_{CH}	Clock Input High Voltage	3.5V	$0.7V_{CC}$	V_{CC}+0.3	1.3	V	Driven by External Clock Generator	
		5.5V	$0.7V_{CC}$	V_{CC}+0.3	2.5	V	Driven by External Clock Generator	
V_{CL}	Clock Input Low Voltage	3.5V	V_{SS}–0.3	$0.2V_{CC}$	0.7	V	Driven by External Clock Generator	
		5.5V	V_{SS}–0.3	$0.2V_{CC}$	1.5	V	Driven by External Clock Generator	
V_{IH}	Input High Voltage	3.5V	$0.7V_{CC}$	V_{CC}+0.3	1.3	V		
		5.5V	$0.7V_{CC}$	V_{CC}+0.3	2.5	V		
V_{IL}	Input Low Voltage	3.5V	V_{SS}–0.3	$0.2V_{CC}$	0.7	V		
		5.5V	V_{SS}–0.3	$0.2V_{CC}$	1.5	V		
V_{OH}	Output High Voltage	3.5V	V_{CC}–0.4		3.1	V	I_{OH} = –2.0 mA	
		5.5V	V_{CC}–0.4		4.8	V	I_{OH} = –2.0 mA	
V_{OL1}	Output Low Voltage	3.5V		0.6	0.2	V	I_{OL} = +4.0 mA	
		5.5V		0.4	0.1	V	I_{OL} = +4.0 mA	
V_{OL2}	Output Low Voltage	3.5V		1.2	0.5	V	I_{OL} = +6 mA	
		5.5V		1.2	0.5	V	I_{OL} = +12 mA	
V_{RH}	Reset Input High Voltage	3.5V	$0.5V_{CC}$	V_{CC}	1.1	V		
		5.5V	$0.5V_{CC}$	V_{CC}	2.2	V		
V_{RL}	Reset Input Low Voltage	3.5V	V_{SS}–0.3	$0.2V_{CC}$	0.9	V		
		5.5V	V_{SS}–0.3	$0.2V_{CC}$	1.4	V		
V_{OFFSET}	Comparator Input Offset Voltage	3.5V		25.0	10.0	mV		
		5.5V		25.0	10.0	mV		
I_{IL}	Input Leakage	3.5V	–1.0	2.0	0.064	mA	V_{IN} = 0V, V_{CC}	
		5.5V	–1.0	2.0	0.064	mA	V_{IN} = 0V, V_{CC}	
I_{OL}	Output Leakage	3.5V	–1.0	2.0	0.114	µA	V_{IN} = 0V, V_{CC}	
		5.5V	–1.0	2.0	0.114	µA	V_{IN} = 0V, V_{CC}	
V_{ICR}	Comparator Input Common Mode Voltage Range	3.5V	V_{SS}–0.3	V_{CC}–1.0		V		3
		5.5V	V_{SS}–0.3	V_{CC}–1.0		V		3
I_{IR}	Reset Input Current	3.5V	–10	–60	–30	µA		
		5.5V	–20	–180	–100	µA		

Table 2. DC Electrical Characteristics (Continued)

			T_A = –40°C to +105°C Extended Temperatures					
Sym	**Parameter**	**V_{CC}[1]**	**Min**	**Max**	**Typical[2] @ 25°C**	**Units**	**Conditions**	**Notes**
I_{CC}	Supply Current	4.5V		7.0	4.0	mA	@ 10 MHz	4,5
		5.5V		7.0	4.0	mA	@ 10 MHz	4,5
I_{CC1}	Standby Current	4.5V		2.0	1.0	mA	HALT Mode V_{IN} = 0V, V_{CC} @ 10 MHz	4,5
		5.5V		2.0	1.0	mA	HALT Mode V_{IN} = 0V, V_{CC} @ 10 MHz	4,5
I_{CC2}	Standby Current	4.5V		700	250	nA	STOP Mode V_{IN} = 0V,V_{CC}	6
		5.5V		700	250	nA	STOP Mode V_{IN} = 0V,V_{CC}	6

Notes:
1. The V_{CC} voltage specification of 4.5V and 5.5V guarantees 5.0V ±0.5V.
2. Typical values are measured at V_{CC} = 3.3V and V_{CC} = 5.0V; V_{SS} = 0V = GND.
3. For analog comparator input when analog comparator is enabled.
4. All outputs unloaded and all inputs are at V_{CC} or V_{SS} level.
5. CL1 = CL2 = 22 pF.
6. Same as note 4 except inputs at V_{CC}.

AC ELECTRICAL CHARACTERISTICS

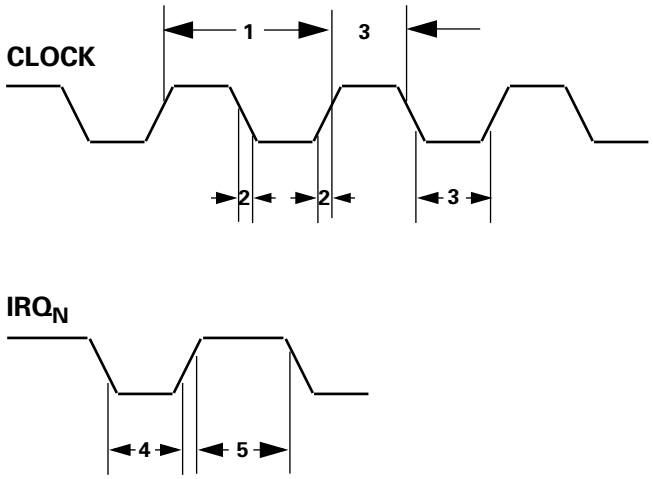


Figure 8. AC Electrical Timing Diagram

Table 3. Additional Timing

				T_A = 0°C to +70°C T_A = –40°C to +105°C @ 10 MHz			
No	**Symbol**	**Parameter**	**V_{CC}[1]**	**Min**	**Max**	**Units**	**Notes**
1	TpC	Input Clock Period	3.5V	100	DC	ns	2
			5.5V	100	DC	ns	2
2	TrC,TfC	Clock Input Rise and Fall Times	3.5V		15	ns	2
			5.5V		15	ns	2
3	TwC	Input Clock Width	3.5V	50		ns	2
			5.5V	50		ns	2
4	TwIL	Int. Request Input Low Time	3.5V	70		ns	2
			5.5V	70		ns	2
5	TwIH	Int. Request Input High Time	3.5V	5TpC			2
			5.5V	5TpC			2
6	Twsm	STOP Mode Recovery Width Spec.	3.5V	12		ns	
			5.5V	12		ns	
7	Tost	Oscillator Start-Up Time	3.5V		5TpC		
			5.5V		5TpC		

Notes:
1. The V_{DD} voltage specification of 3.5V guarantees 3.5V. The V_{DD} voltage specification of 5.5V guarantees 5.0V ±0.5V.
2. Timing Reference uses 0.7 V_{CC} for a logic 1 and 0.2 V_{CC} for a logic 0.

Z8PLUS CORE

The Z8E001 is based on the ZiLOG Z8Plus Core Architecture. This core is capable of addressing up to 64KBytes of program memory and 4KBytes of RAM. Register RAM is accessed as either 8 or 16 bit registers using a combination of 4, 8, and 12 bit addressing modes. The architecture supports up to 15 vectored interrupts from external and internal sources. The processor decodes 44 CISC instructions using six addressing modes. See the Z8Plus User's Manual for more information.

RESET

This section describes the Z8E001 reset conditions, reset timing, and register initialization procedures. Reset is generated by the Reset Pin, Watch-Dog Timer (WDT), and Stop-Mode Recovery (SMR).

A system reset overrides all other operating conditions and puts the Z8E001 into a known state. To initialize the chip's internal logic, the RESET input must be held Low for at least 30 XTAL clock cycles. The control registers and ports are reset to their default conditions after a reset from the RESET pin. The control registers and ports are not reset to their default conditions after wakeup from Stop Mode or WDT timeout.

During $\overline{\text{RESET}}$, the program counter is loaded with 0020H. I/O ports and control registers are configured to their default reset state. Resetting the Z8E001 does not affect the contents of the general-purpose registers.

RESET PIN OPERATION

The Z8E001 hardware $\overline{\text{RESET}}$ pin initializes the control and peripheral registers, as shown in Table 4. Specific reset values are shown by 1 or 0, while bits whose states are unchanged or unknown from Power-Up are indicated by the letter U.

$\overline{\text{RESET}}$ must be held Low until the oscillator stabilizes, for an additional 30 XTAL clock cycles, in order to be sure that the internal reset is complete. The RESET pin has a Schmitt-Trigger input with a trip point. There is no High side protection diode. The user should place an external diode from $\overline{\text{RESET}}$ to V_{CC}. A pull-up resistor on the $\overline{\text{RESET}}$ pin is approximately 500 KΩ, typical.

Program execution starts 10 XTAL clock cycles after $\overline{\text{RESET}}$ has returned High. The initial instruction fetch is from location 0020H. Figure 9 indicates reset timing.

After a reset, the first routine executed must be one that initializes the TCTLHI control register to the required system configuration, followed by initialization of the remaining control registers.

Table 4. Control and Peripheral Registers

		Bits								
Register (HEX)	**Register Name**	**7**	**6**	**5**	**4**	**3**	**2**	**1**	**0**	**Comments**
FF	Stack Pointer	0	0	U	U	U	U	U	U	Stack pointer is not affected by RESET
FE	Reserved									
FD	Register Pointer	U	U	U	U	0	0	0	0	Register pointer is not affected by RESET
FC	Flags	U	U	U	U	U	U	*	*	Only WDT & SMR flags are affected by RESET
FB	Interrupt Mask	0	0	0	0	0	0	0	0	All interrupts masked by $\overline{\text{RESET}}$
FA	Interrupt Request	0	0	0	0	0	0	0	0	All interrupt requests cleared by RESET
F9–F0	Reserved									
EF–E0	Virtual Copy									Virtual Copy of the Current Working Register Set
DF–D8	Reserved									

Table 5. Flag Register Bit D1, D0

D1	D0	Reset Source
0	0	RESET Pin
0	1	SMR Recovery
1	0	WDT Reset
1	1	Reserved

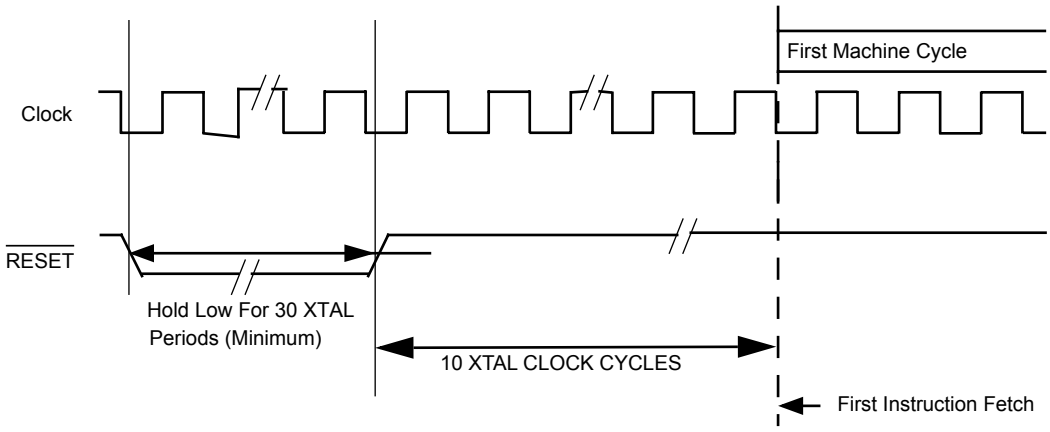


Figure 9. Reset Timing

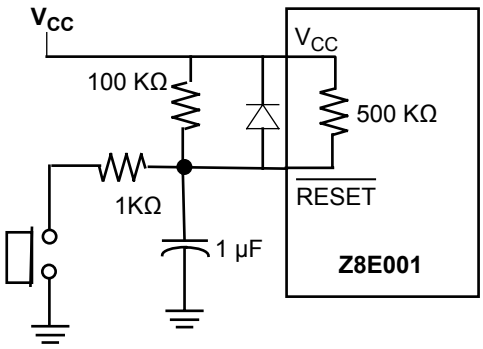


Figure 10. Example of External Power-On Reset (POR) Circuit

Note: The WDT can only be disabled via software if the first instruction out of RESET performs this function. Logic within the Z8E001 detects that it is in the process of executing the first instruction after the part leaves RESET. During the execution of this instruction, the upper five bits of the TCTLHI register can be written. After this first instruction, hardware does not allow the upper five bits of this register to be written.

The TCTLHI bits for control of the WDT are described below:

WDT Time Select (D6, D5, D4). Bits 6, 5, and 4 determine the time-out period. Table 6 indicates the range of timeout values that can be obtained. The default values of D6, D5, and D4 are all 1, thus setting the WDT to its maximum timeout period when coming out of RESET.

WDT During HALT (D7). This bit determines whether or not the WDT is active during HALT Mode. A 1 indicates active during HALT. A 0 prevents the WDT from resetting the part while halted.Coming out of reset, the WDT is enabled during HALT Mode.

STOP MODE (D3). Coming out of RESET, the Z8E001 STOP Mode is disabled. If an application requires use of STOP Mode, bit D3 must be cleared immediately upon leaving RESET. If bit D3 is set, the STOP instruction executes as a NOP. If bit D3 is cleared, the STOP instruction enters Stop Mode. Whenever the Z8E001 wakes up after having been in STOP Mode, the STOP Mode is again disabled.

Bits 2, 1 and 0. These bits are reserved and must be 0.

Table 6. WDT Time-Out

D6	D5	D4	Crystal Clocks* to Timeout	Time-Out Using a 10 MHZ Crystal
0	0	0	Disabled	Disabled
0	0	1	65,536 TpC	6.55 ms
0	1	0	131,072 TpC	13.11 ms
0	1	1	262,144 TpC	26.21 ms
1	0	0	524,288 TpC	52.43 ms
1	0	1	1,048,576 TpC	104.86 ms
1	1	0	2,097,152 TpC	209.72 ms
1	1	1	4,194,304 TpC	419.43 ms

Note:
*TpC=XTAL clock cycle. The default on reset is D6=D5=D4=1.

POWER-DOWN MODES

In addition to the standard RUN mode, the Z8E001 MCU supports two Power-Down modes to minimize device current consumption. The two modes supported are HALT and STOP.

HALT MODE OPERATION

The HALT Mode suspends instruction execution and turns off the internal CPU clock. The on-chip oscillator circuit remains active so the internal clock continues to run and is applied to the timers and interrupt logic.

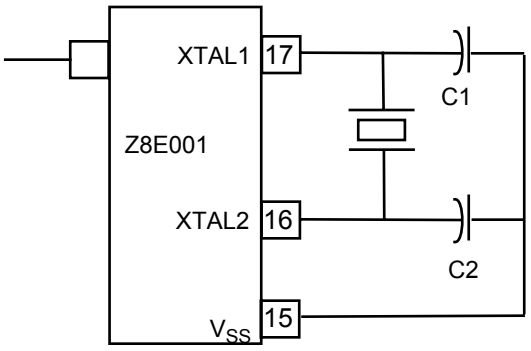
To enter the HALT Mode, the Z8E001 only requires a HALT instruction. It is NOT necessary to execute a NOP instruction immediately before the HALT instruction.

```
7F      HALT            ; enter HALT Mode
```

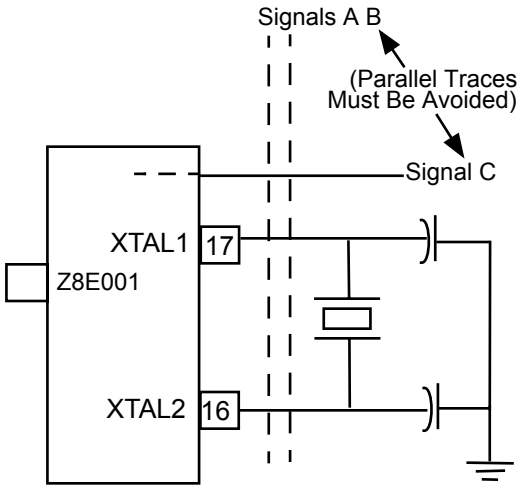
The HALT Mode can be exited by servicing an interrupt (either externally or internally) generated. Upon completion of the interrupt service routine, the user program continues from the instruction after the HALT instruction.

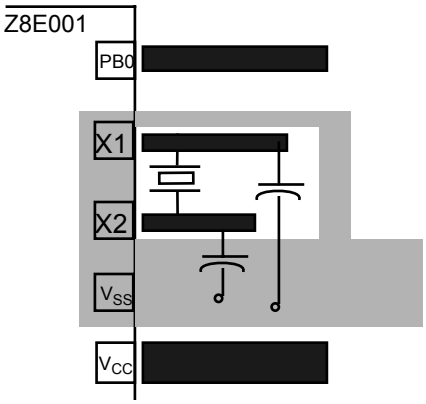
The HALT Mode can also be exited via a RESET activation or a Watch-Dog Timer (WDT) timeout. In these cases, program execution restarts at the reset restart address 0020H.

- V_{CC} power lines should be separated from the clock oscillator input circuitry.
- Resistivity between XTAL1 or XTAL2 (and the other pins) should be greater than 10 MΩ.



Clock Generator Circuit





Board Design Example

(Top View)

Figure 15. Circuit Board Design Rules

Crystals and Resonators

Crystals and ceramic resonators (Figure 16) should have the following characteristics to ensure proper oscillation:

Crystal Cut	AT (crystal only)
Mode	Parallel, Fundamental Mode
Crystal Capacitance	<7pF
Load Capacitance	10pF < CL < 220 pF,
	15 typical
Resistance	100 ohms max

Depending on the operation frequency, the oscillator can require additional capacitors, C1 and C2, as shown in Figure 16 and Figure 17. The capacitance values are dependent on the manufacturer's crystal specifications.

OSCILLATOR OPERATION (Continued)

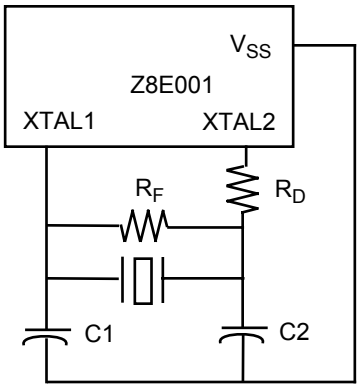


Figure 16. Crystal/Ceramic Resonator Oscillator

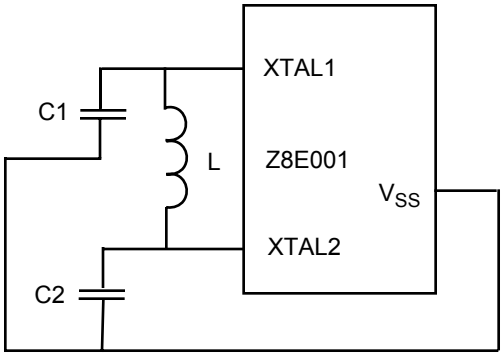


Figure 17. LC Clock

In most cases, the R_D is 0 Ohms and R_F is infinite. These specifications are determined and specified by the crystal/ceramic resonator manufacturer. The R_D can be increased to decrease the amount of drive from the oscillator output to the crystal. It can also be used as an adjustment to avoid clipping of the oscillator signal to reduce noise. The R_F can be used to improve the start-up of the crystal/ceramic resonator. The Z8E001 oscillator already has an internal shunt resistor in parallel to the crystal/ceramic resonator.

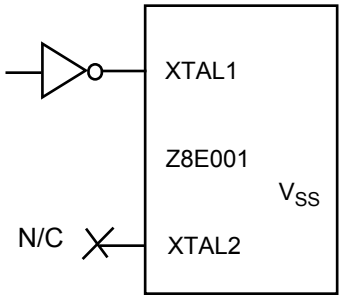


Figure 18. External Clock

Figure 16, Figure 17, and Figure 18 recommend that the load capacitor ground trace connect directly to the V_{SS} (GND) pin of the Z8E001. This requirement assures that no system noise is injected into the Z8E001 clock. This trace should not be shared with any other components except at the V_{SS} pin of the Z8E001.

Note: A parallel resonant crystal or resonator data sheet specifies a load capacitor value that is a series combination of C_1 and C_2, including all parasitics (PCB and holder).

PORT A REGISTER DIAGRAMS

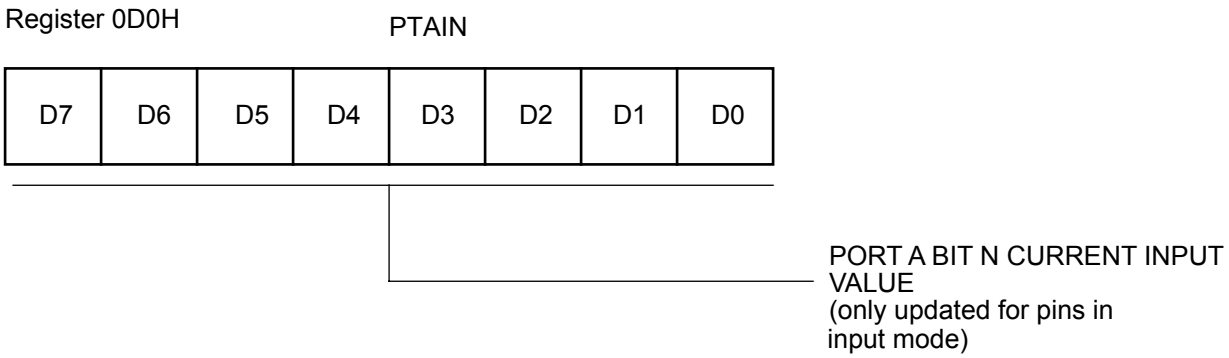


Figure 28. Port A Input Value Register

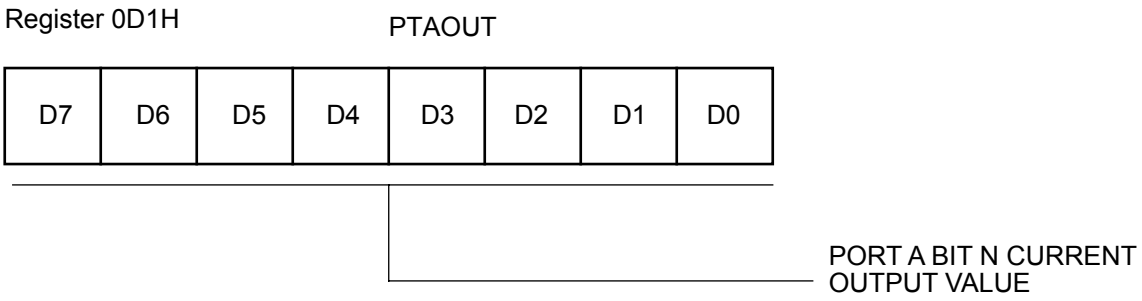


Figure 29. Port A Output Value Register

PORT B—PIN 0 CONFIGURATION

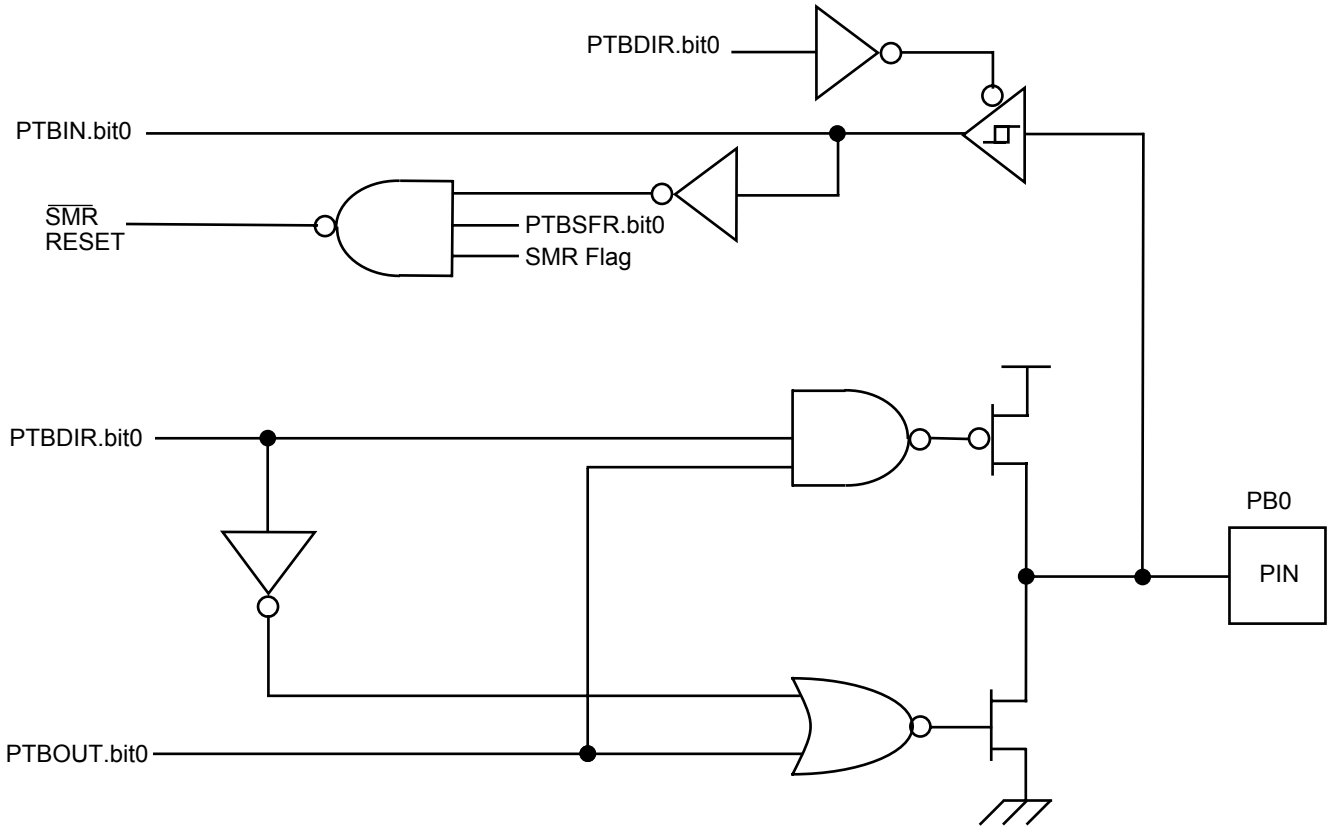


Figure 33. Port B Pin 0 Diagram

PORT B CONTROL REGISTERS

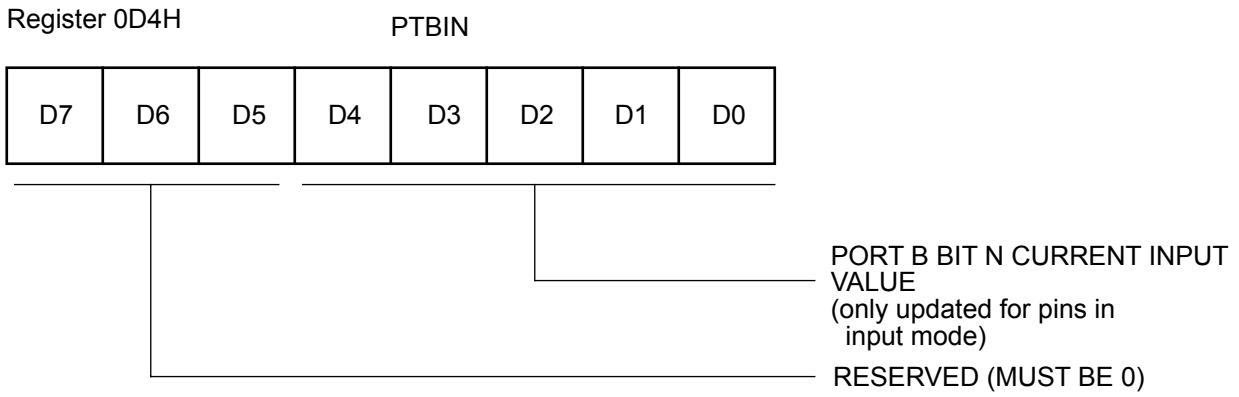


Figure 37. Port B Input Value Register

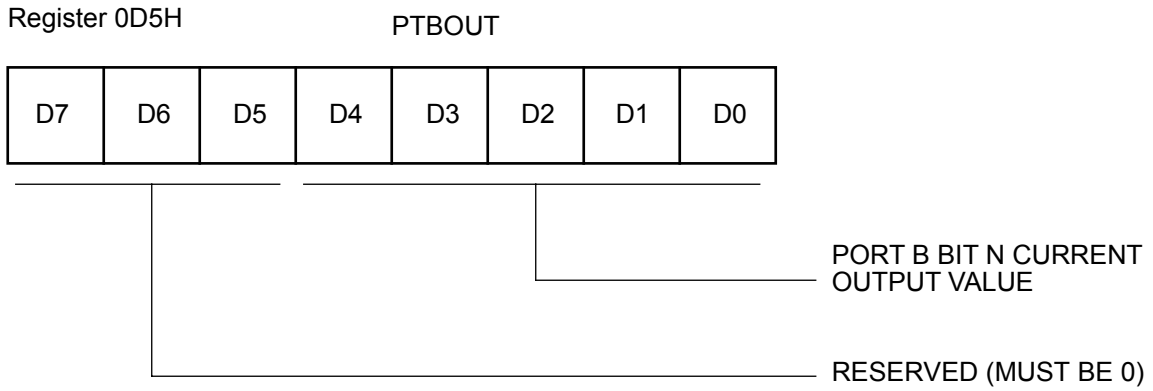


Figure 38. Port B Output Value Register

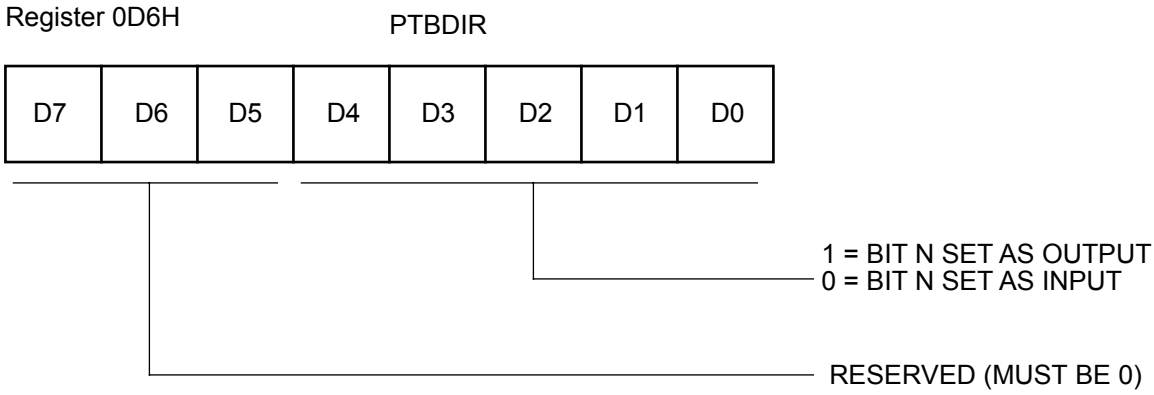


Figure 39. Port B Directional Control Register

I/O PORT RESET CONDITIONS

Full Reset

Port A and Port B output value registers are not affected by RESET.

On $\overline{\text{RESET}}$, the Port A and Port B directional control registers is cleared to all zeros, which defines all pins in both ports as inputs.

On $\overline{\text{RESET}}$, the directional control registers redefine all pins as inputs, and the Port A and Port B input value registers overwrites the previously held data with the current sample of the input pins.

On $\overline{\text{RESET}}$, the Port A and Port B special function registers is cleared to all zeros, which deactivates all port special functions.

Note: The SMR and WDT timeout events are NOT full device resets. The port control registers are not affected by either of these events.

ANALOG COMPARATOR

The Z8E001 includes one on-chip analog comparator. Pin PB4 has a comparator front end. The comparator reference voltage is on pin PB3.

Comparator Description

The on-chip comparator can process an analog signal on PB4 with reference to the voltage on PB3. The analog function is enabled by programming the Port B Special Function Register bits 3 and 4.

When the analog comparator function is enabled, bit 4 of the input register is defined as holding the synchronized output of the comparator, while bit 3 retains a synchronized sample of the reference input.

If the interrupts for PB4 are enabled when the comparator special function is selected, the output of the comparator generates interrupts.

COMPARATOR OPERATION

The comparator output reflects the relationship between the analog input to the reference input. If the voltage on the analog input is higher than the voltage on the reference input, then the comparator output is at a High state. If the voltage on the analog input is lower than the voltage on the reference input, then the analog output will be at a Low state.

Comparator Definitions

V_{ICR}

The usable voltage range for the positive input and reference input is called the common mode voltage range (V_{ICR}).

Note: The comparator is not guaranteed to work if the input is outside of the V_{ICR} range.

V_{OFFSET}

The absolute value of the voltage between the positive input and the reference input required to make the comparator output voltage switch is the input offset voltage (V_{OFFSET}).

I_{IO}

For the CMOS voltage comparator input, the input offset current (I_{IO}) is the leakage current of the CMOS input gate.

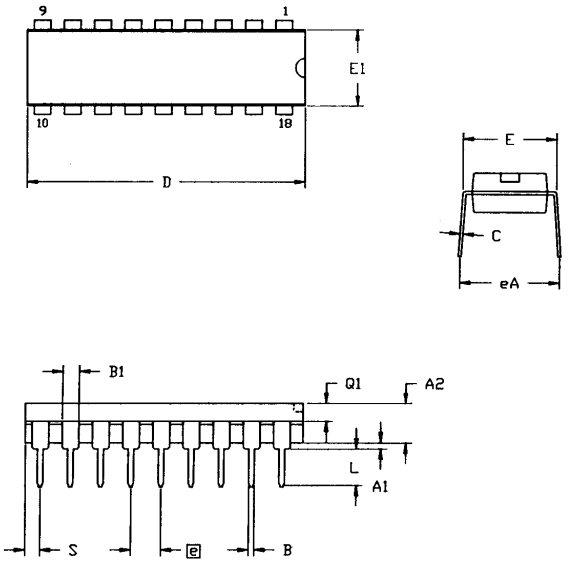
HALT Mode

The analog comparator is functional during HALT Mode. If the interrupts are enabled, an interrupt generated by the comparator will cause a return from HALT Mode.

STOP Mode

The analog comparator is disabled during STOP Mode. The comparator is powered down to prevent it from drawing any current.

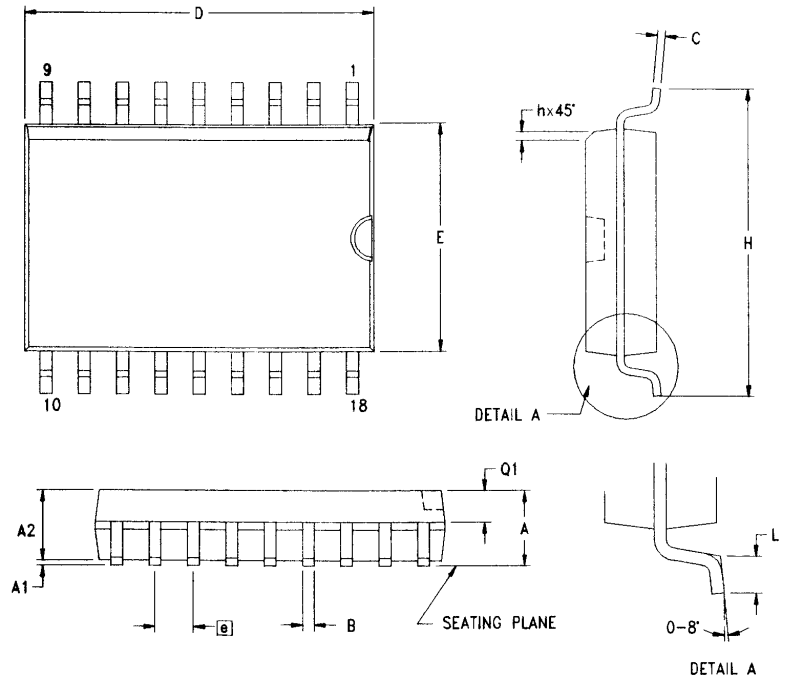
PACKAGE INFORMATION



SYMBOL	MILLIMETER		INCH	
	MIN	MAX	MIN	MAX
A1	0.51	0.81	.020	.032
A2	3.25	3.43	.128	.135
B	0.38	0.53	.015	.021
B1	1.14	1.65	.045	.065
C	0.23	0.38	.009	.015
D	22.35	23.37	.880	.920
E	7.62	8.13	.300	.320
E1	6.22	6.48	.245	.255
e	2.54 TYP		.100 TYP	
eA	7.87	8.89	.310	.350
L	3.18	3.81	.125	.150
Q1	1.52	1.65	.060	.065
S	0.89	1.65	.035	.065

CONTROLLING DIMENSIONS : INCH

Figure 43. 18-Pin DIP Package Diagram

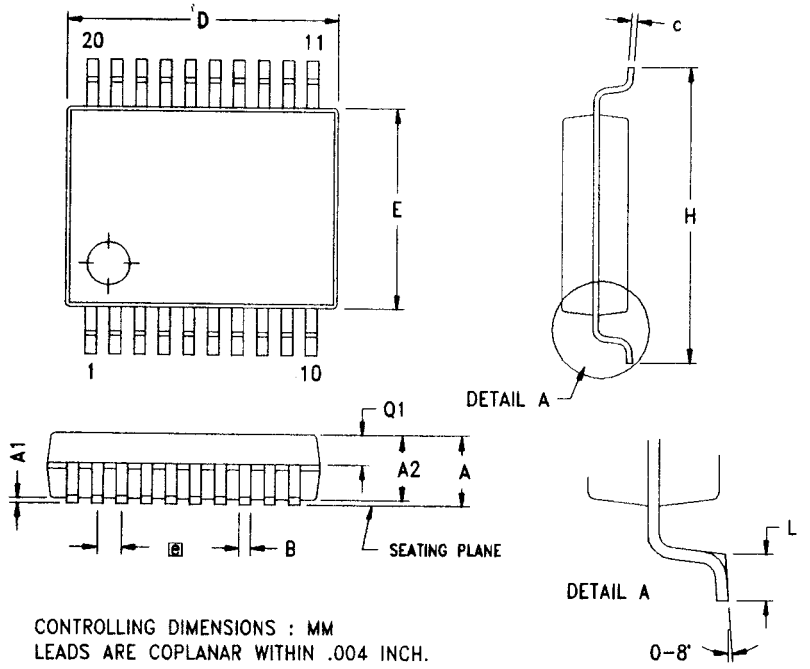


SYMBOL	MILLIMETER		INCH	
	MIN	MAX	MIN	MAX
A	2.40	2.65	0.094	0.104
A1	0.10	0.30	0.004	0.012
A2	2.24	2.44	0.088	0.096
B	0.36	0.46	0.014	0.018
C	0.23	0.30	0.009	0.012
D	11.40	11.75	0.449	0.463
E	7.40	7.60	0.291	0.299
e	1.27 TYP		0.050 TYP	
H	10.00	10.65	0.394	0.419
h	0.30	0.50	0.012	0.020
L	0.60	1.00	0.024	0.039
Q1	0.97	1.07	0.038	0.042

CONTROLLING DIMENSIONS : MM
LEADS ARE COPLANAR WITHIN .004 INCH.

Figure 44. 18-Pin SOIC Package Diagram

PACKAGE INFORMATION (Continued)



SYMBOL	MILLIMETER			INCH		
	MIN	NOM	MAX	MIN	NOM	MAX
A	1.73	1.85	1.98	0.068	0.073	0.078
A1	0.05	0.13	0.21	0.002	0.005	0.008
A2	1.68	1.73	1.83	0.066	0.068	0.072
B	0.25	0.30	0.38	0.010	0.012	0.015
C	0.13	0.15	0.22	0.005	0.006	0.009
D	7.07	7.20	7.33	0.278	0.283	0.289
E	5.20	5.30	5.38	0.205	0.209	0.212
e	0.65 TYP			0.0256 TYP		
H	7.65	7.80	7.90	0.301	0.307	0.311
L	0.56	0.75	0.94	0.022	0.030	0.037
Q1	0.74	0.78	0.82	0.029	0.031	0.032

Figure 45. 20-Pin SSOP Package Diagram

ORDERING INFORMATION

Standard Temperature	
18-Pin DIP	Z8E00110SSC
18-Pin SOIC	Z8E00110HSC
20-Pin SSOP	Z8E00110PSC
Extended Temperature	
18-Pin DIP	Z8E00110PEC
18-Pin SOIC	Z8E00110SEC
20-Pin SSOP	Z8E00110HEC

For fast results, contact your local ZiLOG sales office for assistance in ordering the part(s) required.

Codes	
Preferred Package	P = Plastic DIP
Longer Lead Time	S = SOIC
	H = SSOP
Preferred Temperature	S = 0°C to +70°C
	E = –40°C to +105°C
Speed	10 = 10 MHz
Environmental	C = Plastic Standard

Example:

Z 8E001 10 P S C is a Z86E001, 10 MHz, DIP, 0° to +70°C, Plastic Standard Flow